

**Dr. Wei-Tsu Tseng**(IBM, USA)

Wei-Tsu Tseng is a research staff member in IBM's semiconductor research center in Albany, NY, USA. He has accrued 21 years of experience in IBM and has been leading the CMP R&D activities including process integration, consumable evaluation, post CMP cleaning, and JDP projects with equipment and chemical suppliers. Prior to his current position at IBM, he was a senior application specialist in 3M, MN, and a senior technical staff at GlobalFoundries, Malta, NY as a CMP team lead in Advanced Technology Development (ATD) department from 2015 to 2018. Before joining IBM's semiconductor research & development center in East Fishkill, NY in 2001, he was an assistant professor in National Chiao Tung University and then National Cheng Kung University in Taiwan.

Wei-Tsu has more than 60 patents to his credits. He has published 110+ technical papers and various book chapters covering all different technical aspects of CMP, post-CMP cleaning, low- k dielectrics, Cu plating and interconnects. He is often invited to give technical presentations worldwide at major semiconductor processing related international conferences. He was a guest editor for Nanomaterials special issue on "Innovation in Nanoelectronic Semiconductor Devices and Materials."

Wei-Tsu received his Ph.D. from the University of Texas at Austin in Materials Science and Engineering, and B.S. degree in Metallurgy and Material Science from National Cheng Kung University in Taiwan.